
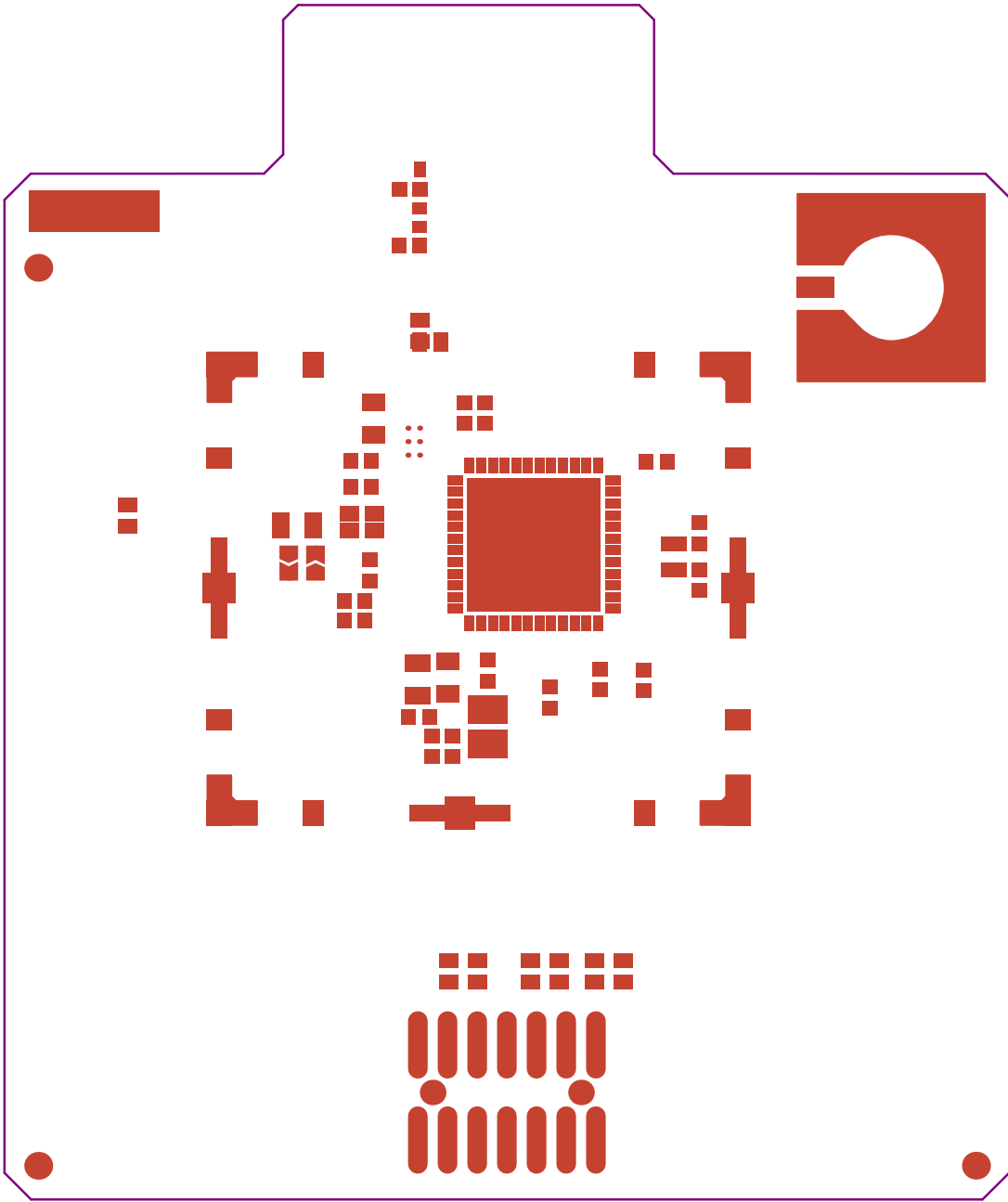

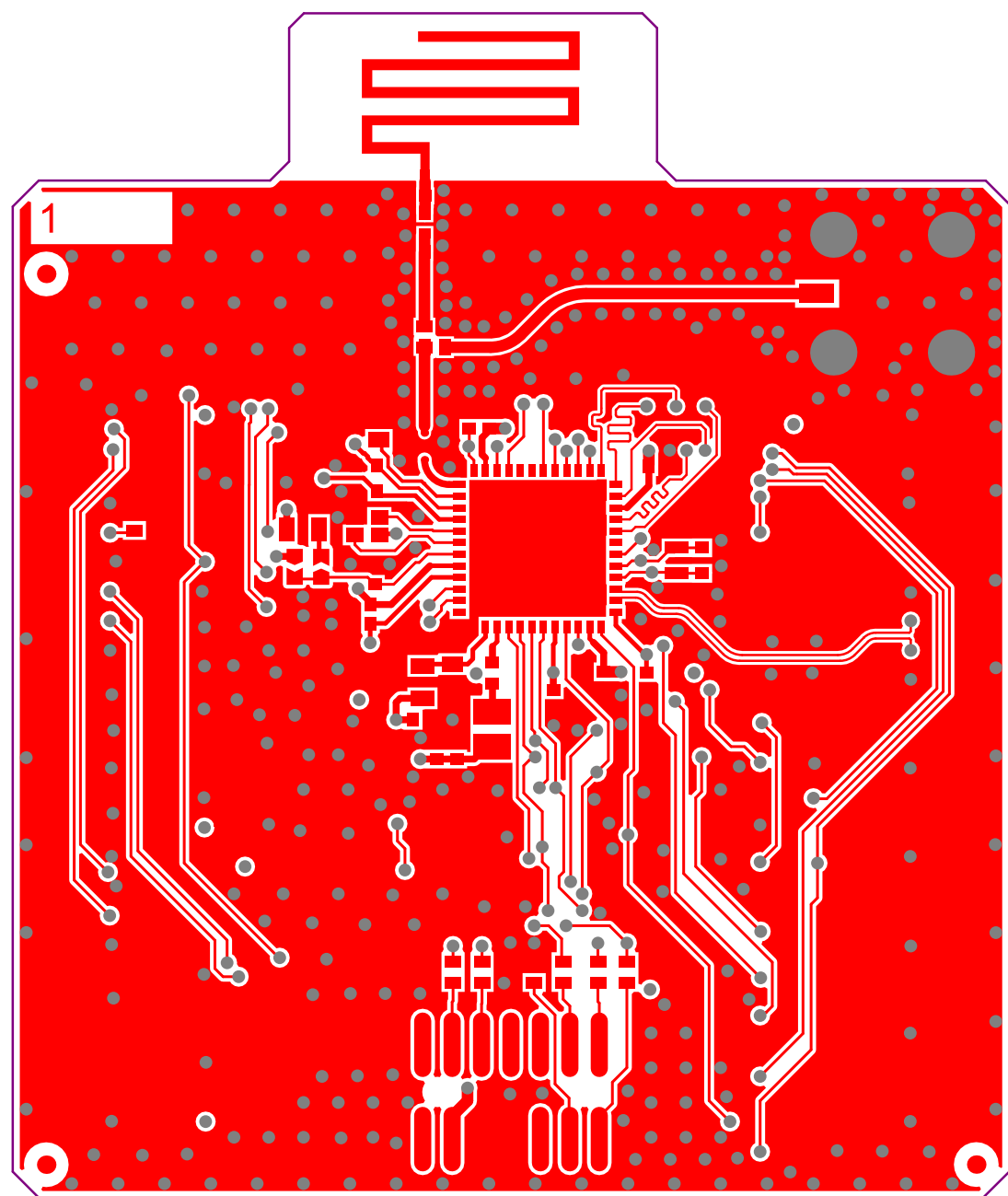



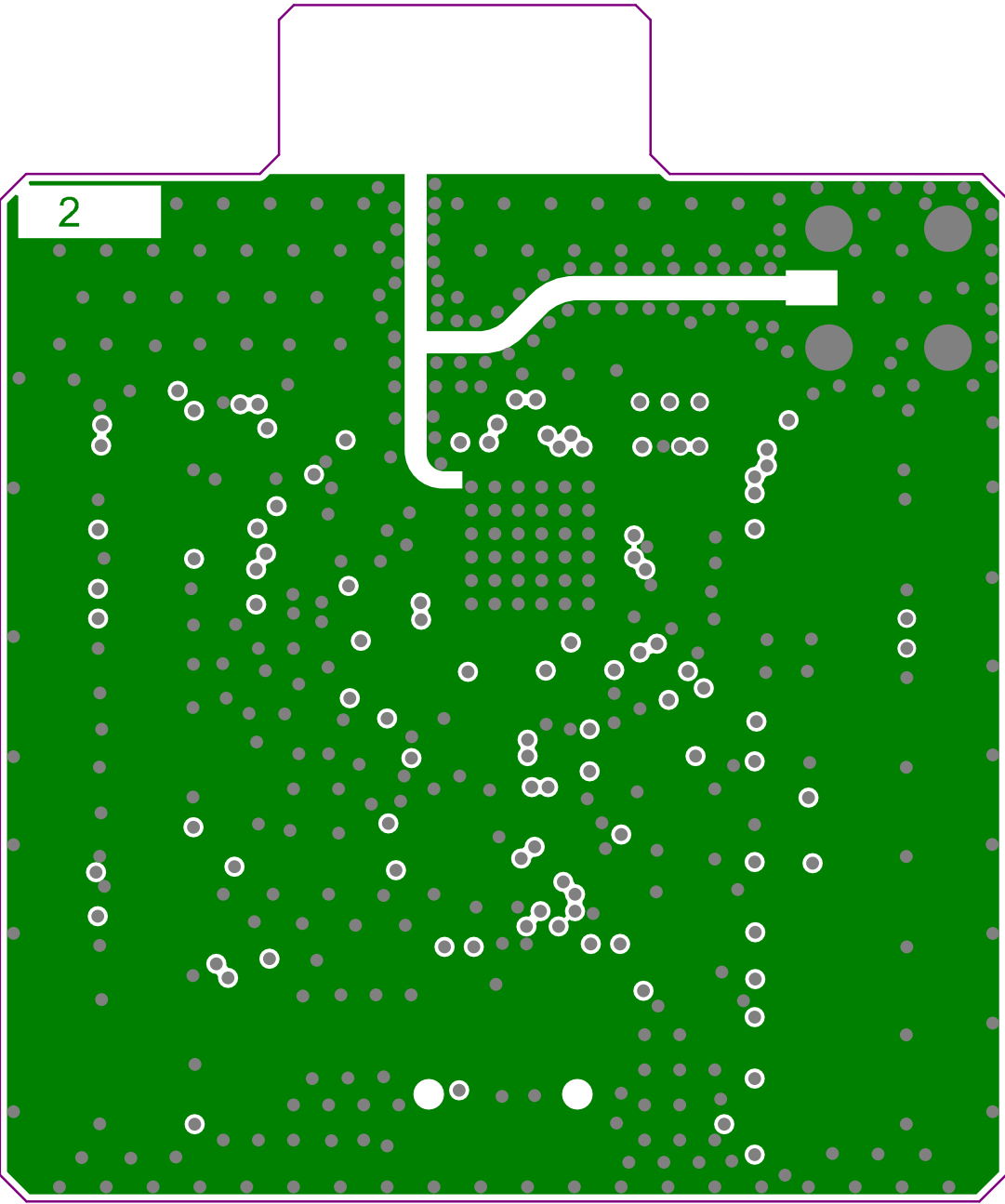
Project: MCU_RF_Board_WBA2_QFN48		
Layer: Top Overlay	Gerber: .GTO	
Variant: [No Variations]	Ref: MB2293	
Date: 27 JAN 2026	Rev: B	




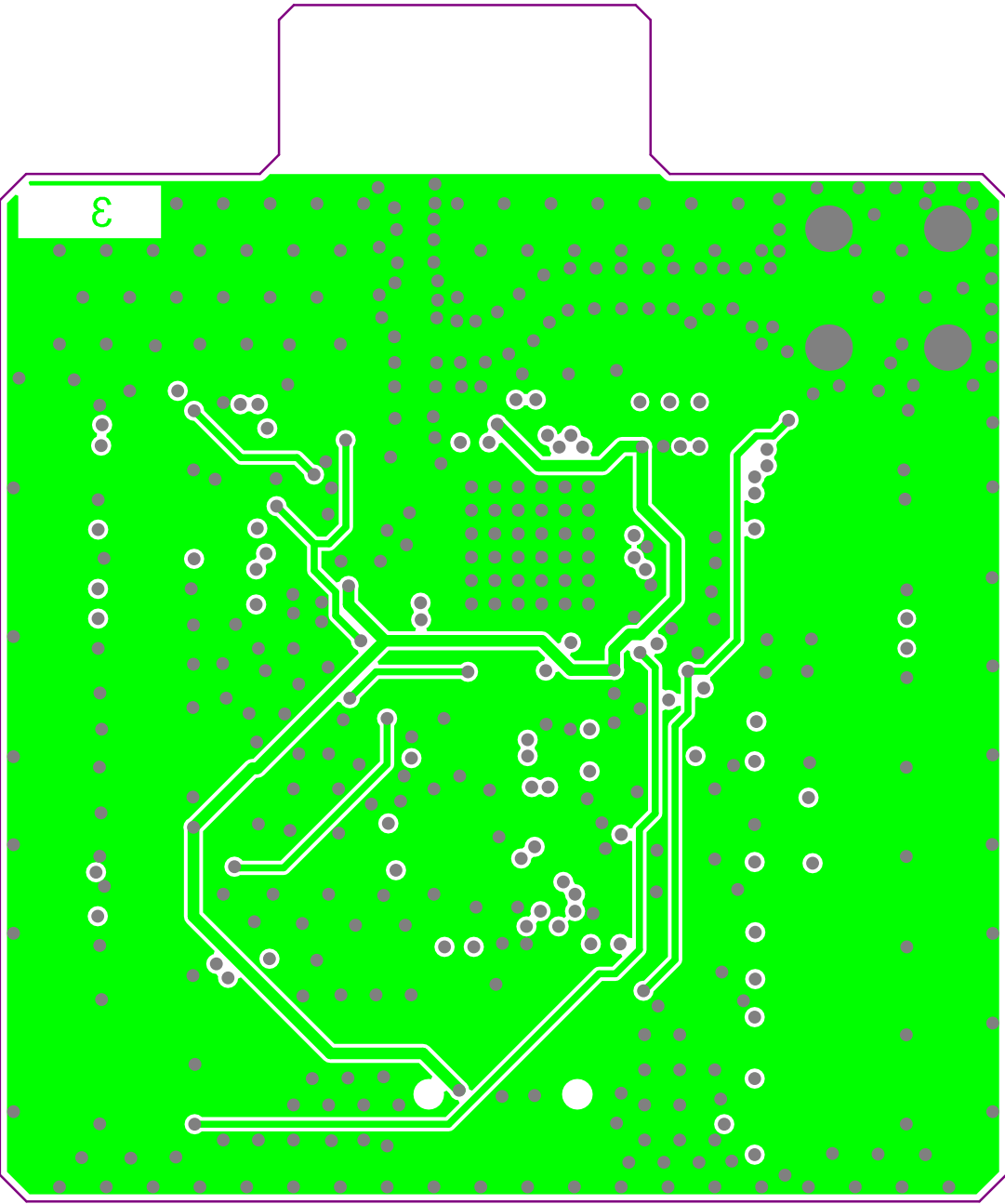
Project: MCU_RF_Board_WBA2_QFN48		
Layer: Top Solder	Gerber: .GTS	
Variant: [No Variations]	Ref: MB2293	
Date: 27 JAN 2026	Rev: B	




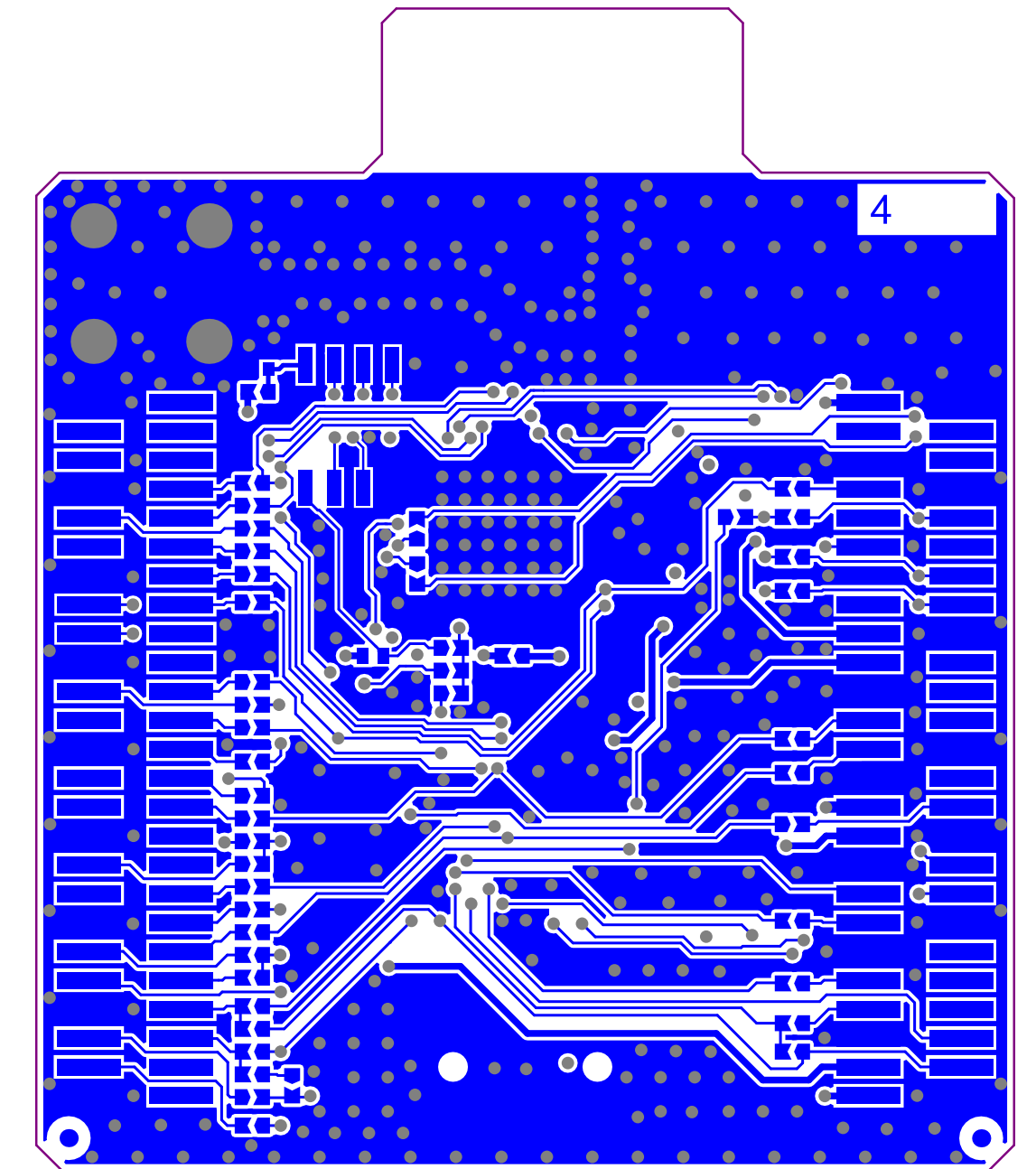
Project: MCU_RF_Board_WBA2_QFN48		
Layer: Top Layer	Gerber: .GTL	
Variant: [No Variations]	Ref: MB2293	
Date: 27 JAN 2026	Rev: B	




Project: MCU_RF_Board_WBA2_QFN48		
Layer: Signal Layer 1	Gerber: .G1	
Variant: [No Variations]	Ref: MB2293	
Date: 27 JAN 2026	Rev: B	




Project: MCU_RF_Board_WBA2_QFN48		
Layer: Signal Layer 2	Gerber: .G2	
Variant: [No Variations]	Ref: MB2293	
Date: 27 JAN 2026	Rev: B	



Project: MCU_RF_Board_WBA2_QFN48		
Layer: Bottom Layer	Gerber: .GBL	
Variant: [No Variations]	Ref: MB2293	
Date: 27 JAN 2026	Rev: B	



Project: MCU_RF_Board_WBA2_QFN48		
Layer: Bottom Solder	Gerber: .GBS	
Variant: [No Variations]	Ref: MB2293	
Date: 27 JAN 2026	Rev: B	

Project: MCU_RF_Board_WBA2_QFN48

Layer: Bottom Overlay

Gerber: .GBO

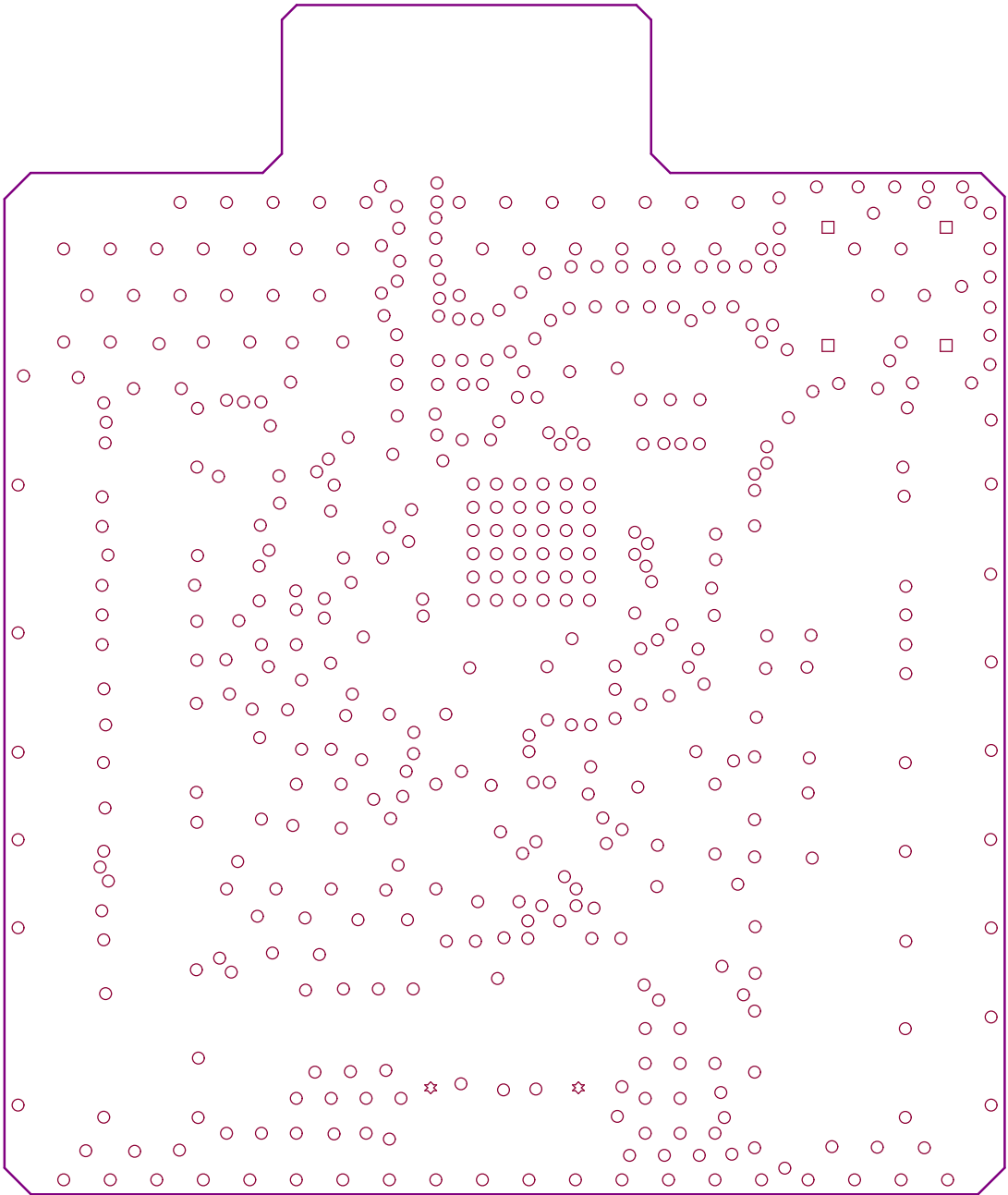
Variant: [No Variations]

Ref: MB2293

Date: 27 JAN 2026


Rev: B





Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0.79mil	3.5	
1	Top Layer		2.76mil		
	Dielectric 1	1080HR RC68	2.99mil	4.2	
2	Signal Layer 1		1.38mil		
	Dielectric 2	FR4	48.43mil	4.5	
3	Signal Layer 2		1.38mil		
	Dielectric 3	1080HR RC68	2.99mil	4.2	
4	Bottom Layer		2.76mil		
	Bottom Solder	Solder Resist	0.79mil	3.5	
	Bottom Overlay				

Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Pad Shape	Template	Description
○	477	13.78mil (0.35mm)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded	v55h35m0mx0	
✱	2	39.37mil (1.00mm)	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c0hn100m110p0	
□	4	43.31mil (1.10mm)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c200h110m210	
	483 Total								

Project: MCU_RF_Board_WBA2_QFN48		
Layer: Drill Drawing	Gerber: .DRL	
Variant: [No Variations]	Ref: MB2293	
Date: 27 JAN 2026	Rev: B	